

SAW RF filter
Automotive telematics
Bluetooth

Series/type: B4360

Ordering code: B39242B4360P810

Date: December 02, 2016

Version: 2.1

© EPCOS AG 2016. Reproduction, publication and dissemination of this data sheet, enclosures hereto and the information contained therein without EPCOS' prior express consent is prohibited.



SAW RF filter 2441.75 MHz

Data sheet

Table of contents

1 Application	3
2 <u>Features</u>	
3 <u>Package</u>	
4 Pin configuration	
5 Matching circuit	
6 Characteristics	
7 <u>Maximum ratings</u>	
8 Transmission coefficient.	
9 Reflection coefficients.	
10 Packing material	
11 <u>Marking</u>	
12 Soldering profile	14
13 ESD protection of SAW filters.	15
14 Annotations.	
15 <u>Cautions and warnings</u>	
Important notes.	



SAW RF filter 2441.75 MHz

Data sheet

1 Application

- Low-loss RF filter for bluetooth
- No external matching components required
- Usable pass band 83.5 MHz

2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- AEC-Q200 qualified component family (Grade 1: -40 °C to +125 °C)



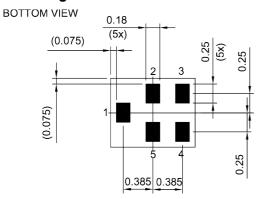
Figure 1: Picture of component with example of product marking.



SAW RF filter 2441.75 MHz

Data sheet

3 Package



Pad and pitch tolerance ±0.05

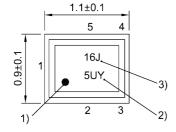
4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW

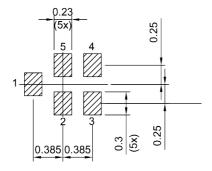


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 17).



SAW components B4360
SAW RF filter 2441.75 MHz

Data sheet

5 Matching circuit

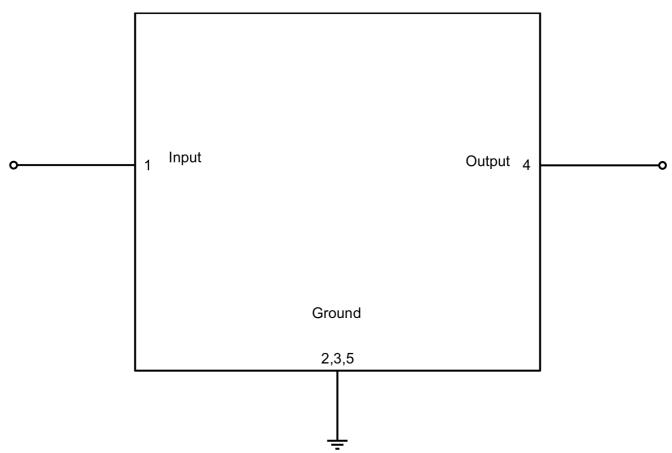


Figure 3: Schematic of matching circuit. No external matching components required.



B4360 **SAW** components

SAW RF filter 2441.75 MHz

Data sheet

Characteristics

 $T_{ ext{SPEC}} \ Z_{ ext{IN}} \ Z_{ ext{OUT}}$ Temperature range for specification = -30 °C ... +85 °C Input terminating impedance = 50 Ω

Output terminating impedance = 50 Ω

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	2441.75	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	2400 2483.5	MHz		_	2.1	3.0	dB
Amplitude ripple (p-p)			Δα				
	2400 2483.5	MHz		_	0.9	1.8	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	2400 2483.5	MHz		_	1.8	2.2	
@ output port	2400 2483.5	MHz		_	1.8	2.2	
Minimum attenuation			$\boldsymbol{\alpha}_{_{min}}$				
	699 787	MHz		24	30	_	dB
	791 960	MHz		22	29	_	dB
	1452 1496	MHz		22	28	_	dB
	1710 2170	MHz		23	28	_	dB
	2570 2620	MHz		24	36	_	dB
	2620 2690	MHz		24	33	_	dB
	3400 3800	MHz		24	31	_	dB



B4360 **SAW** components

SAW RF filter 2441.75 MHz

Data sheet

Maximum ratings

Operable temperature	T _{OP} = -40 °C +125 °C	
Storage temperature	T _{STG} ¹⁾ = -40 °C +125 °C	
DC voltage	$ V_{DC} ^{2)} = 0 V$	
Input power @ input port: 2400 2483.5 MHz	$P_{IN} = 20 \text{ dBm}$	Continuous wave for 5000 h @ 55 °C.

Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C. In case of applied DC voltage blocking capacitors are mandatory.



SAW RF filter 2441.75 MHz

Data sheet

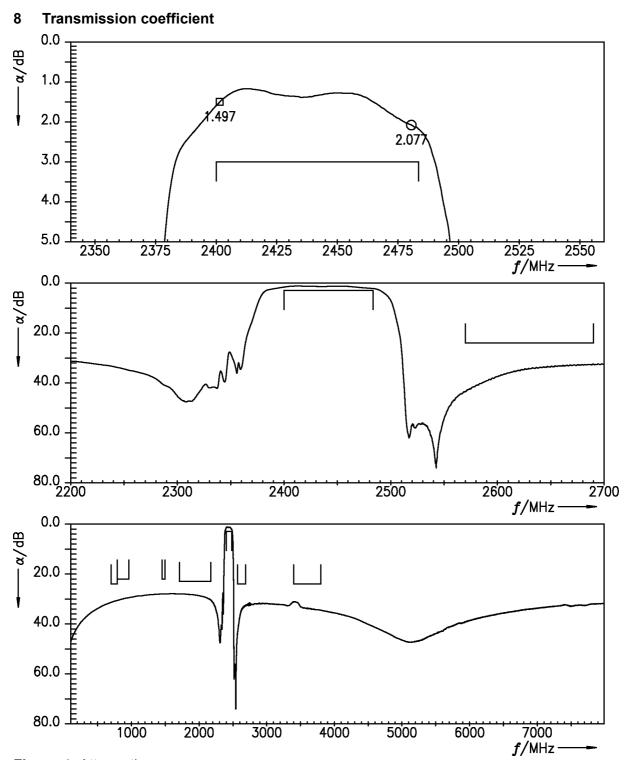


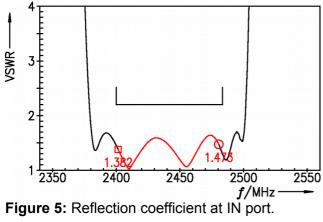
Figure 4: Attenuation.

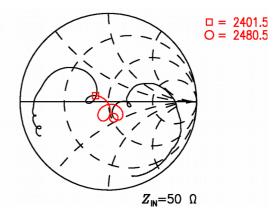


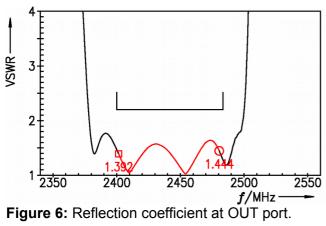
SAW RF filter 2441.75 MHz

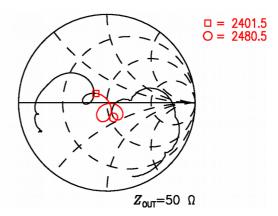
Data sheet

9 **Reflection coefficients**









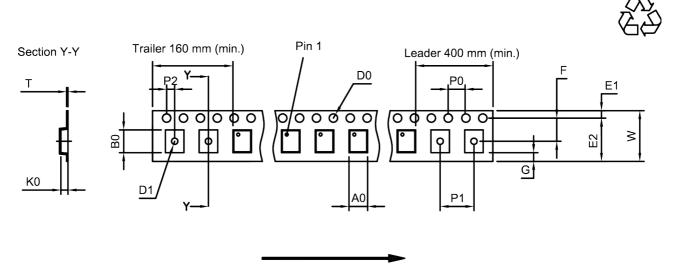


SAW RF filter 2441.75 MHz

Data sheet

10 Packing material

10.1 Tape



User direction of unreeling

Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	1.02±0.05 mm		E ₂	6.25 mm (min.)	P_1	2.0±0.1 mm
B ₀	1.22±0.05 mm		F	3.5±0.05 mm	P_2	2.0±0.05 mm
D ₀	1.55±0.05 mm		G	_	 Т	0.25±0.03 mm
D ₁	0.55±0.1 mm	_	K ₀	0.6±0.05 mm	 W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm		P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.



SAW RF filter 2441.75 MHz

Data sheet

10.2 Reel with diameter of 180 mm

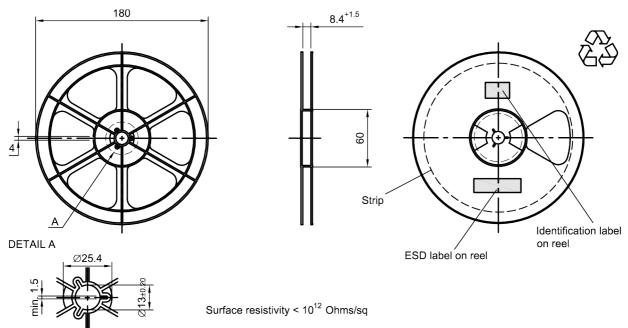


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

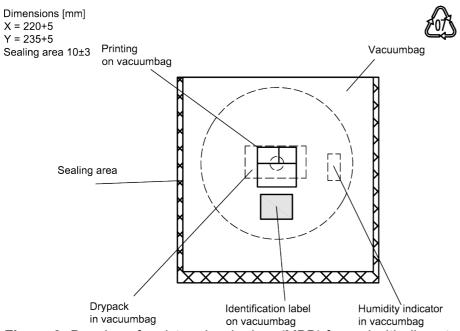


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



SAW RF filter 2441.75 MHz

Data sheet

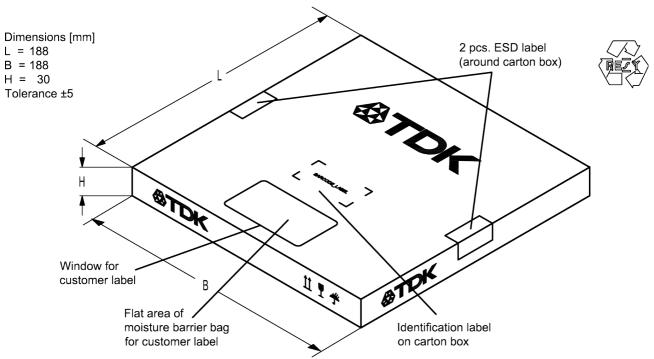


Figure 10: Drawing of folding box for reel with diameter of 180 mm.



SAW RF filter 2441.75 MHz

Data sheet

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x 32^2 + 6 x 32^1 + 18 (=J) x 32^0 = 1234

The BASE32 code for product type B4360 is 488.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 5 x 47² + 27 (=U) x 47¹ + 31 (=Y) x 47⁰ = 12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	M	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	Х	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	T	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	X	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	V	
17	Н	41	\	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	M	45	<	
22	N	46	>	
23	Р			

Table 2: Lists for encoding and decoding of marking.



SAW components B4360
SAW RF filter 2441.75 MHz

Data sheet

12 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T _{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

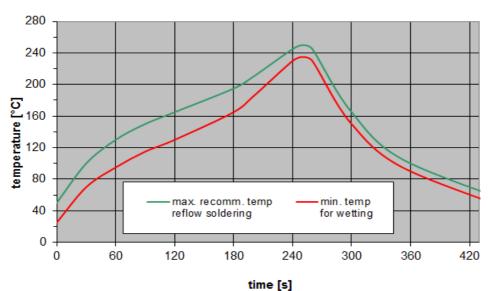


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.



SAW RF filter 2441.75 MHz

Data sheet

13 ESD protection of SAW filters

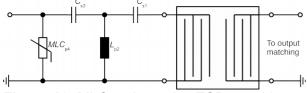
SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, "ESD matching" has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended "ESD matching" topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.



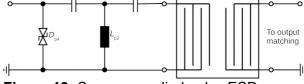


Figure 12: MLC varistor plus ESD matching.

Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified "ESD matching" topologies can be used alternatively.

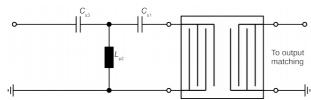


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor $L_{\rm p2}$ could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to EPCOS Application report: "**ESD protection for SAW filters**". This report can be found under www.epcos.com/rke. Click on "Applications Notes".



SAW RF filter 2441.75 MHz

Data sheet

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.



SAW RF filter 2441.75 MHz

Data sheet

15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.



Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.
 - The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.
- 6. Unless otherwise agreed in individual contracts, all orders are subject to the current version of the "General Terms of Delivery for Products and Services in the Electrical Industry" published by the German Electrical and Electronics Industry Association (ZVEI).
- 7. The trade names EPCOS, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CSSP, CTVS, DeltaCap, DigiSiMic, DSSP, ExoCore, FilterCap, FormFit, LeaXield, MiniBlue, MiniCell, MKD, MKK, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PQSine, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SIP5D, SIP5K, TFAP, ThermoFuse, WindCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at www.epcos.com/trademarks.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Signal Conditioning category:

Click to view products by RF360 manufacturer:

Other Similar products are found below:

MAPDCC0001 MAPDCC0004 PD0409J5050S2HF 880157 HHS-109-PIN DC1417J5005AHF AFS14A30-2185.00-T3 AFS14A35-1591.50-T3 B39321R801H210 1A0220-3 JP510S LFB212G45SG8C341 LFB322G45SN1A504 LFL182G45TC3B746 SF2159E 30057 FM-104-PIN CER0813B MAPDCC0005 3A325 40287 41180 ATB3225-75032NCT BD0810N50100AHF BD2425J50200AHF C5060J5003AHF JHS-115-PIN JP503AS DC0710J5005AHF DC2327J5005AHF DC3338J5005AHF 43020 LFB2H2G60BB1C106 LFL15869MTC1B787 X3C19F1-20S XC3500P-20S 10013-20 SF2194E CDBLB455KCAX39-B0 TGL2208-SM, EVAL RF1353C PD0922J5050D2HF 1E1305-3 1F1304-3S 1G1304-30 B0922J7575AHF 2020-6622-20 TP-103-PIN BD1222J50200AHF BD1722J50100AHF